Hitoshi Habuka

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

146
papers1,106
citations16
h-index24
g-index156
ext. papers1,215
ext. citations1.9
avg, IF4.14
L-index

| # | Paper | IF | Citations |
|-----|--|------------------|-----------|
| 146 | Anticorrosive Behavior of Aluminum Nitride Surface Exposed to Chlorine Trifluoride Gas at High Temperatures. <i>ECS Journal of Solid State Science and Technology</i> , 2021 , 10, 034006 | 2 | |
| 145 | Boron-Silicon Film Chemical Vapor Deposition Using Boron Trichloride, Dichlorosilane and Monomethylsilane Gases. <i>ECS Journal of Solid State Science and Technology</i> , 2021 , 10, 064006 | 2 | 1 |
| 144 | Benzoxazine-modified BMI Heat-resistant Resin with Low Dielectric Properties. <i>Transactions of the Japan Institute of Electronics Packaging</i> , 2021 , 14, E20-016-1-E20-016-14 | 0.3 | O |
| 143 | Non-Plasma Dry Etcher Design for 200 mm-Diameter Silicon Carbide Wafer. <i>Materials Science Forum</i> , 2020 , 1004, 167-172 | 0.4 | 0 |
| 142 | Etching Rate Profile of C-Face 4H-SiC Wafer Depending on Total Gas Flow Rate of Chlorine Trifluoride and Nitrogen. <i>Materials Science Forum</i> , 2020 , 1004, 173-179 | 0.4 | 1 |
| 141 | Development of SiC Etching by Chlorine Fluoride Gas. <i>Materials Science Forum</i> , 2020 , 1004, 731-737 | 0.4 | 1 |
| 140 | SiC Epitaxial Reactor Cleaning by ClF3 Gas with the Help of Reaction Heat. <i>Materials Science Forum</i> , 2020 , 1004, 186-192 | 0.4 | |
| 139 | Side wall water outlet design for silicon wafer wet cleaning bath. <i>Materials Science in Semiconductor Processing</i> , 2020 , 110, 104970 | 4.3 | O |
| 138 | Electric Current in Rate Equation for Parallel Plate Plasma-Enhanced Chemical Vapour Deposition of SiC x N y O z Film without Heat Assistance. <i>ECS Journal of Solid State Science and Technology</i> , 2020 , 9, 024017 | 2 | O |
| 137 | Anticorrosive Behavior of SiC x N y O z Film Formed by Non-Heat Assistance Plasma-Enhanced Chemical Vapor Deposition Using Monomethylsilane, Nitrogen and Argon Gases. <i>ECS Journal of Solid State Science and Technology</i> , 2020 , 9, 024001 | 2 | 1 |
| 136 | Temperature Influence on Organic Molecular Interaction on Silicon Oxide Surface In Situ Measured Utilizing a Quartz Crystal Microbalance. <i>ECS Journal of Solid State Science and Technology</i> , 2020 , 9, 1040 | o ² 7 | 1 |
| 135 | Design of a Silicon Carbide Chemical Vapor Deposition Reactor Cleaning Process Using Chlorine Trifluoride Gas Accounting for Exothermic Reaction Heat. <i>ECS Journal of Solid State Science and Technology</i> , 2020 , 9, 104008 | 2 | 1 |
| 134 | Deposition and etching behaviour of boron trichloride gas at silicon surface. <i>Journal of Crystal Growth</i> , 2020 , 529, 125301 | 1.6 | 4 |
| 133 | Quartz crystal microbalance for real-time monitoring chlorosilane gas transport in slim vertical cold wall chemical vapor deposition reactor. <i>Materials Science in Semiconductor Processing</i> , 2020 , 106, 10475 | 94.3 | 1 |
| 132 | Exposure of Tantalum Carbide, Silicon Nitride and Aluminum Nitride to Chlorine Trifluoride Gas. <i>ECS Journal of Solid State Science and Technology</i> , 2019 , 8, P175-P179 | 2 | 5 |
| 131 | High-Temperature Reactor Cleaning Using Chlorine Trifluoride Gas for Silicon Carbide Chemical Vapor Deposition. <i>ECS Journal of Solid State Science and Technology</i> , 2019 , 8, P400-P406 | 2 | 3 |
| 130 | Influence of Metal and Polymer Substrate on SiCxNyOz Film Formation by Non-Heat Assistance Plasma-Enhanced Chemical Vapor Deposition Using Monomethylsilane, Nitrogen and Argon Gases. <i>ECS Journal of Solid State Science and Technology</i> , 2019 , 8, P407-P411 | 2 | 2 |

| 129 | Behavior of Viscous Liquid Byproduct Formed in Exhaust Tube by Silicon Carbide Epitaxial Growth. <i>ECS Journal of Solid State Science and Technology</i> , 2019 , 8, P805-P810 | 2 | О |
|-----|---|---------------------|----------------|
| 128 | High Temperature SiC Reactor Cleaning Using Chlorine Trifluoride Gas Achieved by Purified Pyrolytic Carbon Coating Film. <i>Materials Science Forum</i> , 2019 , 963, 141-145 | 0.4 | 1 |
| 127 | Chlorine Trifluoride Gas Distributor Design for Single-Crystalline C-Face 4H-Silicon Carbide Wafer Etcher. <i>Materials Science Forum</i> , 2019 , 963, 520-524 | 0.4 | 2 |
| 126 | Silicon epitaxial growth accelerated by parallel Langmuir processes using SiH2Cl2 and SiH3CH3 gases. <i>Semiconductor Science and Technology</i> , 2018 , 33, 094002 | 1.8 | 1 |
| 125 | Advantages of a slim vertical gas channel at high SiHCl3 concentrations for atmospheric pressure silicon epitaxial growth. <i>Materials Science in Semiconductor Processing</i> , 2018 , 87, 13-18 | 4.3 | 4 |
| 124 | Yttrium oxide film for protecting quartz glass surface from etching by long-term exposure to chlorine trifluoride gas at room temperature. <i>Materials Science in Semiconductor Processing</i> , 2018 , 83, 211-215 | 4.3 | 3 |
| 123 | Quick and Practical Cleaning Process for Silicon Carbide Epitaxial Reactor. <i>Materials Science Forum</i> , 2018 , 924, 96-99 | 0.4 | |
| 122 | Real time evaluation of silicon epitaxial growth process by exhaust gas measurement using quartz crystal microbalance. <i>Materials Science in Semiconductor Processing</i> , 2018 , 88, 192-197 | 4.3 | 5 |
| 121 | 4H-Silicon Carbide Wafer Surface after Chlorine Trifluoride Gas Etching. <i>Materials Science Forum</i> , 2018 , 924, 369-372 | 0.4 | 1 |
| 120 | Water Outlet Design of Wet Cleaning Bath for 300-mm Diameter Silicon Wafers. <i>ECS Journal of Solid State Science and Technology</i> , 2018 , 7, N123-N127 | 2 | 1 |
| 119 | Increase in silicon film deposition rate in a SiHCl3-SiHx-H2 system. <i>Journal of Crystal Growth</i> , 2017 , 468, 204-207 | 1.6 | 6 |
| 118 | A Method to Adjust Polycrystalline Silicon Carbide Etching Rate Profile by Chlorine Trifluoride Gas. <i>Materials Science Forum</i> , 2017 , 897, 383-386 | 0.4 | 5 |
| 117 | Susceptor Coating Materials Applicable for SiC Reactor Cleaning. <i>Materials Science Forum</i> , 2017 , 897, 99-102 | 0.4 | 8 |
| 116 | Transport phenomena in a slim vertical atmospheric pressure chemical vapor deposition reactor utilizing natural convection. <i>Materials Science in Semiconductor Processing</i> , 2017 , 71, 348-351 | 4.3 | 5 |
| 115 | Parallel langmuir processes for silicon epitaxial growth in a SiHCl3-SiHx-H2 system. <i>Materials Science in Semiconductor Processing</i> , 2017 , 72, 134-138 | 4.3 | 5 |
| 114 | Non-Heat Assistance Plasma-Enhanced Chemical Vapor Deposition of SiCxNyOzFilm Using Monomethylsilane, Nitrogen and Argon. <i>ECS Journal of Solid State Science and Technology</i> , 2017 , 6, P44 | 3 ² P448 | 8 ⁴ |
| 113 | Mirror Etching of Single Crystalline C-Face 4H-Silicon Carbide Wafer by Chlorine Trifluoride Gas. <i>ECS Journal of Solid State Science and Technology</i> , 2017 , 6, P582-P585 | 2 | 6 |
| 112 | Quick Cleaning Process for Silicon Carbide Chemical Vapor Deposition Reactor. <i>ECS Journal of Solid State Science and Technology</i> , 2017 , 6, P526-P530 | 2 | 11 |

| 111 | Formation and Removal of Carbon Film on Silicon Carbide Surface Using Chlorine Trifluoride Gas. <i>ECS Journal of Solid State Science and Technology</i> , 2016 , 5, P441-P445 | 2 | 3 |
|-----|--|-----|----|
| 110 | Repetition of In Situ Cleaning Using Chlorine Trifluoride Gas for Silicon Carbide Epitaxial Reactor. <i>ECS Journal of Solid State Science and Technology</i> , 2016 , 5, P12-P15 | 2 | 12 |
| 109 | Non-heat assistance chemical vapor deposition of amorphous silicon carbide using monomethylsilane gas under argon plasma. <i>Surface and Coatings Technology</i> , 2016 , 285, 255-261 | 4.4 | 7 |
| 108 | Slim Water Injection Nozzle for Silicon Wafer Wet Cleaning Bath. <i>Advances in Chemical Engineering and Science</i> , 2016 , 06, 345-354 | 0.4 | 4 |
| 107 | Reflector Influence on Rapid Heating of Minimal Manufacturing Chemical Vapor Deposition Reactor. <i>ECS Journal of Solid State Science and Technology</i> , 2016 , 5, P280-P284 | 2 | 5 |
| 106 | In Situ Measurement for Evaluating Temperature Change Related to Silicon Film Formation in a SiHCl3-H2System. <i>ECS Journal of Solid State Science and Technology</i> , 2016 , 5, P16-P20 | 2 | 3 |
| 105 | Surface and gas phase reactions induced in a trichlorosilaneBiHx system for silicon film deposition. <i>Surface and Coatings Technology</i> , 2015 , 272, 273-277 | 4.4 | 5 |
| 104 | In Situ Cleaning Process of Silicon Carbide Epitaxial Reactor. <i>ECS Journal of Solid State Science and Technology</i> , 2015 , 4, P137-P140 | 2 | 14 |
| 103 | Evaluation of Molecular Interaction between Organic Molecules Physisorbed on Silicon Native Oxide Surface in Dry and Humid Atmosphere. <i>ECS Journal of Solid State Science and Technology</i> , 2015 , 4, P86-P90 | 2 | 4 |
| 102 | Cleaning Process for Using Chlorine Trifluoride Gas Silicon Carbide Chemical Vapor Deposition Reactor. <i>Materials Science Forum</i> , 2015 , 821-823, 125-128 | 0.4 | 3 |
| 101 | Chlorine Trifluoride Gas Transport and Etching Rate Distribution in Silicon Carbide Dry Etcher. <i>Materials Science Forum</i> , 2015 , 821-823, 553-556 | 0.4 | 7 |
| 100 | In Situ Method for Determining Combination of Organic Compounds Interacting with Each Other on Silicon Oxide Surface. <i>ECS Journal of Solid State Science and Technology</i> , 2015 , 4, P408-P414 | 2 | 1 |
| 99 | Numerical evaluation of silicon epitaxial growth on a 450 mm diameter substrate. <i>Physica Status Solidi (A) Applications and Materials Science</i> , 2015 , 212, 1539-1543 | 1.6 | 2 |
| 98 | In-situ observation of chemical vapor deposition using SiHCl3 and BCl3 gases. <i>Physica Status Solidi C: Current Topics in Solid State Physics</i> , 2015 , 12, 953-957 | | 2 |
| 97 | By-Product Formation in a Trichlorosilane-Hydrogen System for Silicon Film Deposition. <i>ECS Journal of Solid State Science and Technology</i> , 2015 , 4, P16-P19 | 2 | 11 |
| 96 | Metal Fluorides Produced Using Chlorine Trifluoride Gas. <i>Journal of Surface Engineered Materials and Advanced Technology</i> , 2015 , 05, 228-236 | 0.2 | 10 |
| 95 | Low temperature amorphous silicon carbide thin film formation process on aluminum surface using monomethylsilane gas and trichlorosilane gas. <i>Journal of Crystal Growth</i> , 2014 , 401, 523-526 | 1.6 | 1 |
| 94 | Precipitates Caused in Silicon Wafers by Prolonged High-Temperature Annealing in Nitrogen Atmosphere. <i>Materials Research Society Symposia Proceedings</i> , 2014 , 1591, 1 | | |

(2012-2014)

| 93 | Cleaning Process Applicable to Silicon Carbide Chemical Vapor Deposition Reactor. <i>ECS Journal of Solid State Science and Technology</i> , 2014 , 3, N3006-N3009 | 2 | 13 |
|----|--|-----|----|
| 92 | Off-Orientation Influence on C-Face (0001) 4H-SiC Surface Morphology Produced by Etching Using Chlorine Trifluoride Gas. <i>Materials Science Forum</i> , 2014 , 778-780, 734-737 | 0.4 | |
| 91 | Precipitates formed in silicon wafers by prolonged high-temperature annealing in nitrogen atmosphere. <i>Japanese Journal of Applied Physics</i> , 2014 , 53, 05FJ05 | 1.4 | 2 |
| 90 | Development of Silicon Carbide Dry Etcher Using Chlorine Trifluoride Gas. <i>Materials Science Forum</i> , 2014 , 778-780, 738-741 | 0.4 | 6 |
| 89 | Room Temperature and Reduced Pressure Chemical Vapor Deposition of Silicon Carbide on Various Materials Surface. <i>Advances in Chemical Engineering and Science</i> , 2014 , 04, 389-395 | 0.4 | 1 |
| 88 | Langasite crystal microbalance frequency behavior over wide gas phase conditions for chemical vapor deposition. <i>Surface and Coatings Technology</i> , 2013 , 230, 312-315 | 4.4 | 7 |
| 87 | Silicon Chemical Vapor Deposition Process Using a Half-Inch Silicon Wafer for Minimal Manufacturing System. <i>Physics Procedia</i> , 2013 , 46, 230-238 | | 6 |
| 86 | Precipitates caused by prolonged high-temperature annealing in floating zone silicon wafer grown from Czochralski single-crystal rod. <i>Materials Science in Semiconductor Processing</i> , 2013 , 16, 923-927 | 4.3 | 3 |
| 85 | Chemical vapor deposition of amorphous silicon carbide thin films on metal surfaces using monomethylsilane gas at low temperatures. <i>Surface and Coatings Technology</i> , 2013 , 217, 88-93 | 4.4 | 11 |
| 84 | Crystalline Defects in Silicon Wafer Caused by Prolonged High-Temperature Annealing in Nitrogen Atmosphere. <i>Advanced Materials Research</i> , 2013 , 699, 445-449 | 0.5 | |
| 83 | Amorphous Silicon Carbide Film Formation at Room Temperature by Monomethylsilane Gas. <i>Materials Science Forum</i> , 2013 , 740-742, 235-238 | 0.4 | |
| 82 | Off-Orientation Influence on C-Face (0001) 4H-SiC Surface Morphology Produced by Etching Using Chlorine Trifluoride Gas. <i>ECS Journal of Solid State Science and Technology</i> , 2013 , 2, N3025-N3027 | 2 | 1 |
| 81 | Surface Chemical Reaction Model of Silicon Dioxide Film Etching by Dilute Hydrogen Fluoride Using a Single Wafer Wet Etcher. <i>ECS Journal of Solid State Science and Technology</i> , 2013 , 2, P264-P267 | 2 | 8 |
| 80 | Numerical calculation model of a single wafer wet etcher using a swinging nozzle. <i>Materials Science in Semiconductor Processing</i> , 2012 , 15, 543-548 | 4.3 | 8 |
| 79 | Langasite Crystal Microbalance Used for In-Situ Monitoring of Amorphous Silicon Carbide Film Deposition. <i>ECS Journal of Solid State Science and Technology</i> , 2012 , 1, P62-P65 | 2 | 7 |
| 78 | Room Temperature Process for Chemical Vapor Deposition of Amorphous Silicon Carbide Thin Film Using Monomethylsilane Gas. <i>Materials Research Society Symposia Proceedings</i> , 2012 , 1433, 83 | | |
| 77 | Density of Etch Pits on C-Face 4H-SiC Surface Produced by ClF3 Gas. <i>Materials Science Forum</i> , 2012 , 725, 49-52 | 0.4 | 7 |
| 76 | Silicon Epitaxial Growth Rate and Transport Phenomena in a Vertical Stacked-Type Multi-Wafer Reactor. <i>Japanese Journal of Applied Physics</i> , 2012 , 51, 026701 | 1.4 | |

| 75 | Density and Behavior of Etch Pits on C-Face 4H-SiC Surface Produced by CIF3 Gas. <i>Materials Science Forum</i> , 2012 , 717-720, 379-382 | 0.4 | 6 |
|----|--|-----|----|
| 74 | Concentration of Three Organic Compounds Influencing each other on Silicon Surface. <i>Solid State Phenomena</i> , 2012 , 187, 303-306 | 0.4 | |
| 73 | Silicon Epitaxial Growth Rate and Transport Phenomena in a Vertical Stacked-Type Multi-Wafer Reactor. <i>Japanese Journal of Applied Physics</i> , 2012 , 51, 026701 | 1.4 | |
| 72 | Mechanism of Silicon Carbide Film Deposition at Room Temperature Using Monomethylsilane Gas. <i>Journal of the Electrochemical Society</i> , 2011 , 158, H352 | 3.9 | 11 |
| 71 | Low temperature SiC film deposition using trichlorosilane gas and monomethylsilane gas. <i>Journal of Nanoscience and Nanotechnology</i> , 2011 , 11, 8374-7 | 1.3 | 3 |
| 70 | Room temperature process for chemical vapor deposition of amorphous silicon carbide thin film using monomethylsilane gas. <i>Surface and Coatings Technology</i> , 2011 , 206, 1503-1506 | 4.4 | 7 |
| 69 | Silicon epitaxial growth process using trichlorosilane gas in a single-wafer high-speed substrate rotation reactor. <i>Journal of Crystal Growth</i> , 2011 , 327, 1-5 | 1.6 | 24 |
| 68 | Langasite Crystal Microbalance for Development of Reactive Surface Preparation of Silicon Carbide Film Deposition from Monomethylsilane Gas. <i>Japanese Journal of Applied Physics</i> , 2011 , 50, 096505 | 1.4 | 4 |
| 67 | Silicon Surface Morphology after Annealing in Ambient Hydrogen Containing a Trace Amount of Hydrogen Halide Gas. <i>Japanese Journal of Applied Physics</i> , 2011 , 50, 025701 | 1.4 | |
| 66 | Etch Pits on 4H-SiC Surface Produced by ClF3 Gas. <i>Materials Science Forum</i> , 2011 , 679-680, 286-289 | 0.4 | 1 |
| 65 | Water Motion over a Wafer Surface Rotating in a Single-Wafer Wet Cleaner. <i>ECS Transactions</i> , 2011 , 41, 279-286 | 1 | 2 |
| 64 | Water Motion over a Wafer Surface Rotating in a Single-Water Wet Cleaner. <i>Journal of the Electrochemical Society</i> , 2011 , 158, H487 | 3.9 | 10 |
| 63 | Langasite Crystal Microbalance for Development of Reactive Surface Preparation of Silicon Carbide Film Deposition from Monomethylsilane Gas. <i>Japanese Journal of Applied Physics</i> , 2011 , 50, 096505 | 1.4 | 2 |
| 62 | Advance of Atomic Layer Deposition in Semiconductor Materials Manufacturing Process: Cleaning Technology for Thin Film Formation Reactor. <i>Journal of the Vacuum Society of Japan</i> , 2011 , 54, 97-104 | | |
| 61 | Silicon Surface Morphology after Annealing in Ambient Hydrogen Containing a Trace Amount of Hydrogen Halide Gas. <i>Japanese Journal of Applied Physics</i> , 2011 , 50, 025701 | 1.4 | |
| 60 | Dominant Forces for Driving Bubbles in a Wet Cleaning Bath Using Megasonic Wave. <i>Journal of the Electrochemical Society</i> , 2010 , 157, H585 | 3.9 | 12 |
| 59 | Molecular Interaction Radii and Rate Constants for Clarifying Organic Compound Physisorption on Silicon Surface. <i>Journal of the Electrochemical Society</i> , 2010 , 157, H1014 | 3.9 | 10 |
| 58 | 4H-SiC Surface Morphology Etched Using ClF3 Gas. <i>Materials Science Forum</i> , 2010 , 645-648, 787-790 | 0.4 | 9 |

(2005-2010)

| 57 | Silicon carbide film deposition at low temperatures using monomethylsilane gas. <i>Surface and Coatings Technology</i> , 2010 , 204, 1432-1437 | 4.4 | 18 |
|----|---|----------------|----|
| 56 | Temperature-Dependent Behavior of 4H-Silicon Carbide Surface Morphology Etched Using Chlorine Trifluoride Gas. <i>Journal of the Electrochemical Society</i> , 2009 , 156, H971 | 3.9 | 21 |
| 55 | Hafnium Oxide Film Etching Using Hydrogen Chloride Gas. <i>Japanese Journal of Applied Physics</i> , 2009 , 48, 125503 | 1.4 | 2 |
| 54 | Etching Rate of Silicon Dioxide Using Chlorine Trifluoride Gas. <i>Japanese Journal of Applied Physics</i> , 2009 , 48, 026504 | 1.4 | 8 |
| 53 | Water and Bubble Motions Under Megasonic Wave in a Silicon Wafer Wet Cleaning Bath. <i>ECS Transactions</i> , 2009 , 25, 265-272 | 1 | 3 |
| 52 | Etching Rate Behavior of 4H-Silicon Carbide Using Chlorine Trifloride Gas. <i>ECS Transactions</i> , 2008 , 13, 39-52 | 1 | 8 |
| 51 | Heat Transport and Temperature Gradient in Silicon-on-Insulator Wafer during Flash Lamp Annealing Process. <i>Japanese Journal of Applied Physics</i> , 2008 , 47, 6277-6281 | 1.4 | 2 |
| 50 | 4H Silicon Carbide Etching Using Chlorine Trifluoride Gas. <i>Materials Science Forum</i> , 2008 , 600-603, 655-6 | 5584 | 10 |
| 49 | Decarbonation and Pore Structural Change of Ca-Solid Reactant for CaO/CO2 Chemical Heat Pump. <i>Journal of Chemical Engineering of Japan</i> , 2008 , 41, 513-518 | 0.8 | 5 |
| 48 | Polycrystalline silicon carbide film deposition using monomethylsilane and hydrogen chloride gases. <i>Journal of Crystal Growth</i> , 2007 , 300, 374-381 | 1.6 | 16 |
| 47 | Water Motion in a Water Curtain Head for Cleaning a Large Glass Plate. <i>Japanese Journal of Applied Physics</i> , 2007 , 46, 838-842 | 1.4 | |
| 46 | Determination of Etch Rate Behavior of 4HBiC Using Chlorine Trifluoride Gas. <i>Japanese Journal of Applied Physics</i> , 2007 , 46, 7875-7879 | 1.4 | 22 |
| 45 | Heat Transport Analysis for Flash Lamp Annealing. <i>Japanese Journal of Applied Physics</i> , 2007 , 46, 937-94 | 1 2 1.4 | 20 |
| 44 | Physisorption and Desorption of Diethyl Phthalate and Isopropanol on a Silicon Surface. <i>Journal of the Electrochemical Society</i> , 2007 , 154, H1031 | 3.9 | 9 |
| 43 | Carbonation/Decarbonation of Ca-Solid Reactant Derived from Natural Limestone for Thermal-Energy Storage and Temperature Upgrade. <i>Journal of Chemical Engineering of Japan</i> , 2007 , 40, 1270-1274 | 0.8 | 2 |
| 42 | Small-Batch Reactor Development for Silicon Epitaxial Film Growth Based on Theory of Transport Phenomena. <i>ECS Transactions</i> , 2006 , 2, 21-32 | 1 | 2 |
| 41 | Etch rate and surface morphology of polycrystalline Esilicon carbide using chlorine trifluoride gas. <i>Thin Solid Films</i> , 2006 , 514, 193-197 | 2.2 | 9 |
| 40 | Dominant rate process of silicon surface etching by hydrogen chloride gas. <i>Thin Solid Films</i> , 2005 , 489, 104-110 | 2.2 | 31 |

| 39 | Gas Velocity Influence on Silicon Surface Organic Contamination Evaluated Using Quartz Crystal Microbalance. <i>Journal of the Electrochemical Society</i> , 2005 , 152, G862 | 3.9 | 9 |
|----|--|-----------------|------|
| 38 | Silicon Carbide Etching Using Chlorine Trifluoride Gas. <i>Japanese Journal of Applied Physics</i> , 2005 , 44, 13 | 7 6- 438 | 3126 |
| 37 | Quartz Crystal Microbalance for Silicon Surface Organic Contamination. <i>Journal of the Electrochemical Society</i> , 2005 , 152, G241 | 3.9 | 12 |
| 36 | Highly Concentrated Ozone Gas for Preparing Wettable Polyimide Surface. <i>Japanese Journal of Applied Physics</i> , 2005 , 44, 5225-5230 | 1.4 | 2 |
| 35 | Air Flow in Square Quartz Plate Spin Cleaner. <i>Japanese Journal of Applied Physics</i> , 2005 , 44, 8182-8185 | 1.4 | 2 |
| 34 | Heat Balance Evaluation for Rapid Thermal Processing System Design. <i>Journal of the Electrochemical Society</i> , 2005 , 152, G924 | 3.9 | 5 |
| 33 | Water Motion in Carrierless Wet Station. Journal of the Electrochemical Society, 2004, 151, G814 | 3.9 | 9 |
| 32 | Silicon Etch Rate Using Chlorine Trifluoride. <i>Journal of the Electrochemical Society</i> , 2004 , 151, G783 | 3.9 | 16 |
| 31 | Formation mechanism of local thickness profile of silicon epitaxial film. <i>Journal of Crystal Growth</i> , 2004 , 266, 327-332 | 1.6 | 7 |
| 30 | Time-Dependent Airborne Organic Contamination on Silicon Wafer Surface Stored in a Plastic Box. <i>Japanese Journal of Applied Physics</i> , 2003 , 42, 1575-1580 | 1.4 | 13 |
| 29 | Airborne Organic Contamination Behavior on Silicon Wafer Surface. <i>Journal of the Electrochemical Society</i> , 2003 , 150, G148 | 3.9 | 18 |
| 28 | High-Performance Silicon Etching Using Chlorine Trifluoride Gas. <i>Journal of the Electrochemical Society</i> , 2003 , 150, G461 | 3.9 | 15 |
| 27 | Flatness Deterioration of Silicon Epitaxial Film Formed in a Horizontal Single-Wafer Epitaxial Reactor II. <i>Japanese Journal of Applied Physics</i> , 2002 , 41, 5692-5696 | 1.4 | 5 |
| 26 | Model of boron incorporation into silicon epitaxial film in a B2H6BiHCl3⊞2 system. <i>Journal of Crystal Growth</i> , 2001 , 222, 183-193 | 1.6 | 6 |
| 25 | Hot-wall and cold-wall environments for silicon epitaxial film growth. <i>Journal of Crystal Growth</i> , 2001 , 223, 145-155 | 1.6 | 4 |
| 24 | Design of a Rapid Thermal Processing System Using a Reflection-Resolved Ray Tracing Method. Journal of the Electrochemical Society, 2001 , 148, G543 | 3.9 | 8 |
| 23 | Development of Evaluation Method for Organic Contamination on Silicon Wafer Surfaces. <i>Journal of the Electrochemical Society</i> , 2001 , 148, G644 | 3.9 | 18 |
| 22 | Adsorption and Desorption Rate of Multicomponent Organic Species on Silicon Wafer Surface. Journal of the Electrochemical Society, 2001, 148, G365 | 3.9 | 28 |

(1995-2001)

| 21 | Nonempirical Design of Rapid Thermal Processing System. <i>Japanese Journal of Applied Physics</i> , 2001 , 40, 7123-7128 | 1.4 | 2 |
|----|--|------------------|----|
| 20 | Flatness Deterioration of Silicon Epitaxial Film Formed Using Horizontal Single-Wafer Epitaxial Reactor. <i>Japanese Journal of Applied Physics</i> , 2001 , 40, 6041-6044 | 1.4 | 5 |
| 19 | Instability of diborane gas in silicon epitaxial film growth. Journal of Crystal Growth, 2000, 209, 807-815 | 1.6 | 11 |
| 18 | Rate Theory of Multicomponent Adsorption of Organic Species on Silicon Wafer Surface. <i>Journal of the Electrochemical Society</i> , 2000 , 147, 2319 | 3.9 | 27 |
| 17 | Thermal Conditions in Rapid Thermal Processing System Using Circular Infrared Lamp. <i>Journal of the Electrochemical Society</i> , 2000 , 147, 4660 | 3.9 | 8 |
| 16 | CVD Material Processing. Numerical Calculations of Heat Profile using Circular Infrared Lamp Heating Furnace <i>Kagaku Kogaku Ronbunshu</i> , 2000 , 26, 785-791 | 0.4 | 2 |
| 15 | Dominant Overall Chemical Reaction in a Chlorine TrifluorideBiliconNitrogen System at Atmospheric Pressure. <i>Japanese Journal of Applied Physics</i> , 1999 , 38, 6466-6469 | 1.4 | 8 |
| 14 | A Direct Approach for Evaluating the Thermal Condition of a Silicon Substrate under Infrared Rays and Specular Reflectors. <i>Journal of the Electrochemical Society</i> , 1999 , 146, 713-718 | 3.9 | 12 |
| 13 | Chemical process of silicon epitaxial growth in a SiHCl3⊞2 system. <i>Journal of Crystal Growth</i> , 1999 , 207, 77-86 | 1.6 | 48 |
| 12 | In situ cleaning method for silicon surface using hydrogen fluoride gas and hydrogen chloride gas in a hydrogen ambient. <i>Journal of Crystal Growth</i> , 1998 , 186, 104-112 | 1.6 | 11 |
| 11 | Reaction of Hydrogen Fluoride Gas at High Temperatures with Silicon Oxide Film and Silicon Surface. <i>Japanese Journal of Applied Physics</i> , 1998 , 37, 6123-6127 | 1.4 | 12 |
| 10 | Change in Microroughness of a Silicon Surface during In Situ Cleaning Using HF and HCl Gases. <i>Journal of the Electrochemical Society</i> , 1998 , 145, 4264-4271 | 3.9 | 6 |
| 9 | Haze Generation on Silicon Surface Heated in Hydrogen Ambient at Atmospheric Pressure. <i>Journal of the Electrochemical Society</i> , 1997 , 144, 3261-3265 | 3.9 | 5 |
| 8 | Computation Transport Phenomena in Chemical Engineering. Transport of Dopant Gas during Silicon Epitaxial Thin-Film Growth in a Horizontal Reactor <i>Kagaku Kogaku Ronbunshu</i> , 1997 , 23, 772-77 | 9 ^{0.4} | 2 |
| 7 | Nonlinear increase in silicon epitaxial growth rate in a SiHCl3?H2 system under atmospheric pressure. <i>Journal of Crystal Growth</i> , 1997 , 182, 352-362 | 1.6 | 27 |
| 6 | Effect of Transport Phenomena on Boron Concentration Profiles in Silicon Epitaxial Wafers. <i>Journal of the Electrochemical Society</i> , 1996 , 143, 677-682 | 3.9 | 3 |
| 5 | Model on transport phenomena and epitaxial growth of silicon thin film in SiHCl3?H2 system under atmospheric pressure. <i>Journal of Crystal Growth</i> , 1996 , 169, 61-72 | 1.6 | 75 |
| 4 | Gas flow and heat transfer in a pancake chemical vapor deposition reactor. <i>Journal of Crystal Growth</i> , 1995 , 151, 375-383 | 1.6 | 8 |

| 3 | Roughness of Silicon Surface Heated in Hydrogen Ambient. <i>Journal of the Electrochemical Society</i> , 1995 , 142, 3092-3098 | 3.9 | 29 |
|---|--|-----|----|
| 2 | Modeling of Epitaxial Silicon Thin-Film Growth on a Rotating Substrate in a Horizontal Single-Wafer Reactor. <i>Journal of the Electrochemical Society</i> , 1995 , 142, 4272-4278 | 3.9 | 30 |
| 1 | Numerical Evaluation of Silicon-Thin Film Growth from SiHCl3-H2Gas Mixture in a Horizontal Chemical Vapor Deposition Reactor. <i>Japanese Journal of Applied Physics</i> , 1994 , 33, 1977-1985 | 1.4 | 15 |